Glass Passivated Chip Junction
High current capability
Low forward voltage drop
Low power loss, high efficiency
Lead free in comply w1gs EMC /P <</MCID 87>>BDC>>BD 82>>BDC 20.797 0 TD9( )]TJEM1.3P <</MCID 93>>BDC 3.106 (

Marking Diagram

Ordering information

Model name	Package	Unit Weight	Base Quantity	Packing Quantity
	TO-252	0.011oz(0.32g)	2500pcs/reel	5000pcs/box 25000pcs/Carton

Package Dimensions

TO-252

Dim	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	2.20	2.50	0.087	0.098
A1	0.00	0.12	0.000	0.005
A2	2.20	2.40	0.087	0.094
B	1.20	1.60	0.047	0.063
b	0.50	0.70	0.020	0.028
b1	0.70	0.90	0.028	0.035
c	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.35	6.65	0.250	0.262
D1	5.20	5.40	0.205	0.213
[illegible]	[illegible]	[illegible]	[illegible]	[illegible]
[illegible]	[illegible]	[illegible]	[illegible]	[illegible]
eee P	0.27	4	0	[illegible]

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